## CLAIMS

[Claim 1] A substrate polishing device comprising:

a turntable having a first adhesive surface

a polishing pad having to which a second adhesive surface of a polishing pad is capable of being adhesively fixed, wherein

an adhesive region and a first separation assistance region are provided between the first adhesive surface and the second adhesive surface,

the first adhesive surface and the second adhesive surface are adhered to each other in the adhesive region,

an adhesive force acting between the first adhesive surface and the second adhesive surface in the first separation assistance region is smaller than an adhesive force acting between the first adhesive surface and the second adhesive surface in the adhesive region, and

the first separation assistance region is positioned on an outer circumferential portion of the polishing pad.

[Claim 2] The substrate polishing device according to claim 1, further comprising the polishing pad, wherein

the adhesive region and the first separation assistance region are formed on the second adhesive surface.

[Claim 3] The substrate polishing device according to claim 2, wherein

the polishing pad includes:

a pad-shaped main body portion; and

an adhesive portion which is provided to cover a part of a surface of the main body portion and exhibits an adhesive force,

the adhesive region is a portion of the polishing pad in which the adhesive

portion is provided, and

the first separation assistance region is a portion of the polishing pad in which the adhesive portion is not provided.

[Claim 4] The substrate polishing device according to claim 2, wherein

the polishing pad includes:

a pad-shaped main body portion;

an adhesive portion which is provided to cover a surface of the main body portion and exhibits an adhesive force; and

a low adhesive force portion which is provided to cover a part of a surface of the adhesive portion and exhibits an adhesive force lower than the adhesive force of the adhesive portion,

the adhesive region is a portion of the adhesive portion which is not covered with the low adhesive force portion, and

the first separation assistance region is a portion in which the low adhesive force portion is provided.

[Claim 5] The substrate polishing device according to claim 1, wherein the adhesive region and the first separation assistance region are formed on the first adhesive surface.

[Claim 6] The substrate polishing device according to claim 5, wherein

at least one recessed portion is formed on a surface of the turntable,

the adhesive region is a portion of the turntable in which the recessed portion is not formed, and

the first separation assistance region is a portion of the turntable in which the recessed portion is formed.

[Claim 7] The substrate polishing device according to any one of claims 1 to 6, wherein the first separation assistance region is not in contact with an outer circumferential edge

of the polishing pad when viewed from an axial direction parallel to a central axis of the turntable.

[Claim 8] The substrate polishing device according to any one of claims 1 to 6, wherein

a second separation assistance region is further provided between the first adhesive surface and the second adhesive surface,

an adhesive force acting between the first adhesive surface and the second adhesive surface in the second separation assistance region is smaller than an adhesive force acting between the first adhesive surface and the second adhesive surface in the adhesive region, and

when viewed from an axial direction parallel to a central axis of the turntable, the second separation assistance region is positioned between the central axis and the first separation assistance region.

[Claim 9] A polishing pad adhesively fixed to a turntable having a first adhesive surface, comprising a second adhesive surface adhesively fixed to the first adhesive surface, wherein

an adhesive region and a first separation assistance region which is positioned on an outer circumferential portion of the second adhesive surface are provided on the second adhesive surface,

the adhesive region is a region adhered to the first adhesive surface, and

the first separation assistance region is a region which is adhered to the first adhesive surface with a force lower than a force with which the adhesive region is adhered to the first adhesive surface, or a region which is not adhered to the first adhesive surface.